

ABSTRACT OF THE DISCLOSURE

A method for manufacturing an electronic device includes the steps of forming a first resist pattern on a primary surface of a SAW element, the first resist pattern having openings at positions corresponding to those at which bumps and a sealing frame are to be formed, sequentially forming metals over the first resist pattern, the metals being formed into adhesion layers, barrier metal layers, and solder layers, removing the first resist pattern on the SAW element such that the bumps and the sealing frame are simultaneously formed. When the bumps and the sealing frame of the SAW element are bonded to bond electrodes of the bond substrate, the solder layers are melted and alloyed by heating.